

FAX**Date:** Monday, February 12, 2001**Pages including cover sheet:** 7

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NOTE:

Dear Ms. Clark:

Attached are six pages of transmittal sent to you on December 12, 2000 for payment of Issuance Fee and Drawing Correction of Case 09/314,493 (PTLIN9801). Please let me know if you did not receive the information you requested this morning for a misplaced page by PTO of the document.

Thanks for your help!

Bo-In Lin, Attorney Reg. # 33,948

File

PATENT**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Paul T. Lin : Date: December 12, 2000

Serial No.: 09/314,493 : Group No.: 2823

Filed: May 18, 1999 : Examiner: Collins. D.

Attorney Docket No.: PTLIN-9801

Title: SUBSTRATE ON CHIP (SOC) MULTIPLE CHIP MODULE (MCM) WITH CHIP-SIZE-PACKAGE (CSP) READY CONFIGURATION

To the Assistant Commissioner for Patents:

CORRECTION OF DRAWINGS AND PAYMENT OF ISSUE FEE

Dear Sir:

In response to the Examiner's NOTICE OF ALLOWANCE AND ISSUE FEE DUE mailed on September 12, 2000, a payment of \$620.00 for the issuance of Patent is enclosed. If there is any deficiency in fee, you are authorized to charge it to the deposit account 12-0005. Also enclosed is three pages of drawing correction.

Respectfully submitted

Paul T. Lin

By

Bo-In Lin - Attorney, Registration No. 33,948

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CERTIFICATION UNDER 37 CFR 1.10

I hereby certify that this Payment of Issue Fee and the documents referred to as enclosed therein are being deposited with the United States Postal Service on this date December 12, 2000 in an envelope as "Express Mail Post Office to Addressee" Mailing Label Number "EF246741843US" addressed to the : Box ISSUE FEE, Assistant Commissioner for Patents, Washington, D.C. 20231.

Ching-Lu Lin

(Type or print name of person mailing paper)

Ching Lu Lin

(Signature of person mailing paper)

NOTE: Each paper or fee referred to as enclosed herein has the number of the "Express Mail" mailing label placed thereon to mailing. 37 CFR 1.10(b).

Author: BoInLin <BoInLin@sol.com> at Internet
Date: 5/21/98 4:34 PM
Priority: Normal
TO: Paul T. Lin
Subject: Small Entity Form

Message Contents
In the United States Patent and Trademark Office

First/Sole Applicant: Paul T. Lin
Docket No. PTLIN-9801

Title: SUBSTRATE ON CHIP (SOC) MULTIPLE-CHIP MODULE (MCM) WITH
CHIP-SIZE-PACKAGE (CSP) READY CONFIGURATION

Small Entity Declaration - INDEPENDENT INVENTOR(S)

I hereby declare that I am an independent inventor as defined in Section 1.9(c) of 37 CFR. I have not assigned, granted, conveyed or licensed, and am under no obligation under contract or law to assign, grant, convey, or license any rights in the invention to any person who could not likewise be classified as an independent inventor if that person had made the invention, or in any concern which would not qualify as small business concern or a nonprofit organization.

Paul T. Lin
Signature of the First/(Sole) Inventor
Date

May 21, 1998